

MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA*Advance Information***4 Megabit CMOS SRAM**
User-Configurable Multichip Module

The Motorola 32S128 is a 4-megabit CMOS SRAM module organized as 128K words by 32 bits, 256K x 16 or 512K x 8. The module is constructed on a multilayer ceramic substrate, hermetically sealed, with a welded metal cover, hex-in-line package (HIP) utilizing four 128K x 8 SRAM devices.

This module is compatible with most 66 pin HIP packaged SRAM, EEPROM and Flash memory modules.

The 32S128 is available with access times of 25 to 120 ns over commercial, Industrial, and Military temperature ranges.

Writing to each byte is accomplished when the appropriate chip select ($\overline{CS}$) and write enable ($\overline{WE}$) inputs are both low. Reading the device is accomplished by taking the chip selects low while write enable remains high. Under these conditions the contents of the memory locations specified on the address pins will appear on the data input/output pins.

FEATURES:

- Access Times 25 to 120 ns
- 66-pin, PGA Type, 1.2 inch square HIP Package
- User-Configurable as 128K x 32, 256K x 16 or 512K x 8
- Hermetic Ceramic Package
- Battery Back-Up Operation
- Commercial, Industrial, and Military Temperature Ranges
- TTL Compatible Inputs and Outputs
- Commercial Plus Processing Available
- Low Power CMOS Fully Static Design
- 5 Volt Power Supply
- Built in Decoupling Capacitors and Multiple Ground pins for Low Noise Operation
- Military Temperature Range (- 55°C to + 125°C)
- MIL-STD-883 Compliant Devices (Planned)
- Military Screening and Burn-In Available

Military 32S128**SRAM MULTICHIP MODULE****AVAILABLE AS**

- 1) JAN: N/A
- 2) SMD: Planned
- 3) 883: 32S128-XX/BZCJC
- 4) CMP: 32S128-XX/ *

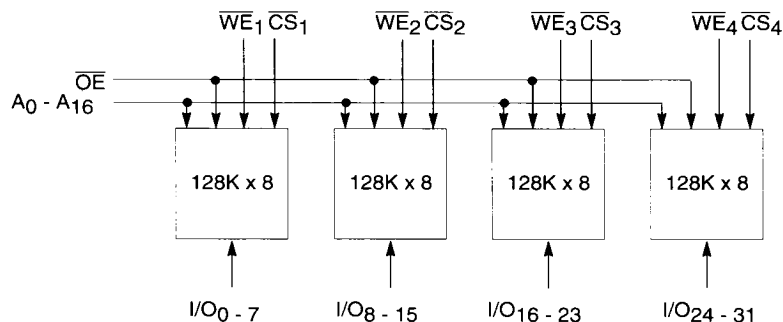
* See Commercial Plus and Avionics Options:
(BR914/D)

PACKAGE: PGA: Z

XX = Speed in ns (25 to 120)
20 ns Planned Q4 1993

PIN NAMES

A ₀ - A ₁₆	Address Inputs
I/O ₀ - I/O ₃₁	Data Input/Output
$\overline{CS}_{1-4}$	Chip Select
$\overline{OE}$	Output Enable
$\overline{WE}_{1-4}$	Write Enable
V _{CC}	+ 5.0 Power
V _{SS}	Ground

BLOCK DIAGRAM

This document contains information on a new product. Specifications and information herein are subject to change without notice.



Pin Assignment

1	12	23	34	45	56
○ I/O ₈	○ $\overline{WE}_2$	○ I/O ₁₅	○ I/O ₂₄	○ V _{CC}	○ I/O ₃₁
○ I/O ₉	○ $\overline{CS}_2$	○ I/O ₁₄	○ I/O ₂₅	○ $\overline{CS}_4$	○ I/O ₃₀
○ I/O ₁₀	○ Gnd	○ I/O ₁₃	○ I/O ₂₆	○ $\overline{WE}_4$	○ I/O ₂₉
○ A ₁₃	○ I/O ₁₁	○ I/O ₁₂	○ A ₆	○ I/O ₂₇	○ I/O ₂₈
○ A ₁₄	○ A ₁₀	○ $\overline{OE}$	○ A ₇	○ A ₃	○ A ₀
○ A ₁₅	○ A ₁₁	○ Gnd	○ Gnd	○ A ₄	○ A ₁
○ A ₁₆	○ A ₁₂	○ $\overline{WE}_1$	○ A ₈	○ A ₅	○ A ₂
○ Gnd	○ V _{CC}	○ I/O ₇	○ A ₉	○ $\overline{WE}_3$	○ I/O ₂₃
○ I/O ₀	○ $\overline{CS}_1$	○ I/O ₆	○ I/O ₁₆	○ $\overline{CS}_3$	○ I/O ₂₂
○ I/O ₁	○ Gnd	○ I/O ₅	○ I/O ₁₇	○ Gnd	○ I/O ₂₁
○ I/O ₂	○ I/O ₃	○ I/O ₄	○ I/O ₁₈	○ I/O ₁₉	○ I/O ₂₀
11	22	33	44	55	66

ABSOLUTE MAXIMUM RATINGS					
Parameter			Symbol	Value	Unit
Operating Temperature			T _A	- 55 to + 125	°C
Storage Temperature Range			T _{STG}	- 65 to + 150	°C
Supply Voltage (Relative to GND)			V _G	- 0.5 to + 7.0	V

TRUTH TABLE					
CS	OE	WE	Mode	Data I/O	Power
H	X	X	Standby	High-Z	Standby (deselect/power down)
L	L	H	Read	Data Out	Active
L	H	H	Read	High-Z	Active (deselect)
L	X	L	Write	Data In	Active

RECOMMENDED OPERATING CONDITIONS				
Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	4.5	5.5	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	- 0.5	+ 0.8	V
CAPACITANCE (@ T _A = 25°C)				
Parameter	Symbol	Condition	Max	Unit
Input Capacitance	C _{IN}	V _{IN} = 0 V, f = 1.0 MHz	30	pF
Output Capacitance	C _{OUT}	V _{OUT} = 0 V, f = 1.0 MHz	30	pF

Periodically sampled rather than 100% tested.

DC CHARACTERISTICS

(V_{CC} = 5 V, T_A = - 55°C to + 125°C)

Parameter	Symbol	Limits		Unit	Test Condition (Unless Otherwise Specified)
		Min	Max		
Input Leakage Current	I _{LI}		8	μA	V _{CC} = Max, V _{IN} = Gnd
Output Leakage Current	I _{LO}		8	μA	$\overline{CS}$ = V _{IH} , $\overline{OE}$ = V _{IH} , V _{OUT} = Gnd to V _{CC} , V _{CC} = Max
Operating Supply Current x 32 mode	I _{CCx32}		450 *	mA	$\overline{CS}$ = V _{IL} , $\overline{OE}$ = V _{IH} , Duty Cycle = Max
Operating Supply Current x 16 mode	I _{CCx16}		280 *	mA	$\overline{CS}$ = V _{IL} , $\overline{OE}$ = V _{IH} , Duty Cycle = Max
Operating Supply Current x 8 mode	I _{CCx8}		150 *	mA	$\overline{CS}$ = V _{IL} , $\overline{OE}$ = V _{IH} , Duty Cycle = Max
Standby Current	I _{SB}		200	mA	$\overline{CS}$ = V _{CC} , $\overline{OE}$ = V _{IH} , Duty Cycle = Max, V _{CC} = Max
Output Low Voltage	V _{OL}		0.4	V	I _{OL} = 2.1 mA (- 70 to 120 ns), I _{OL} = 8 mA (- 25 to - 55 ns)
Output High Voltage	V _{OH}	2.4		V	I _{OH} = - 1.0 mA (for - 70 to - 125 ns)
		2.4		V	I _{OH} = - 4.0 mA (for - 25 to - 55 ns)

AC CHARACTERISTICS

($V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$, $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$)

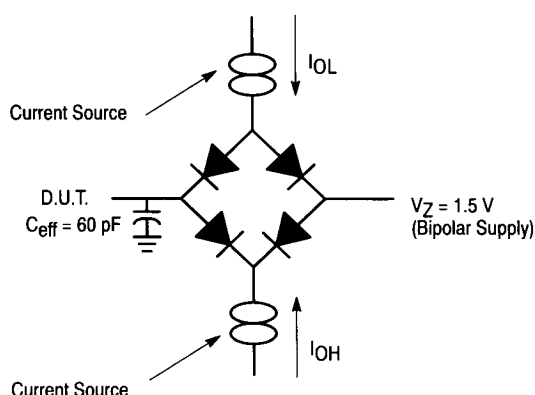
Parameter	Symbol	Limits								Unit
Read Cycle:		- 25		- 35		- 45		- 55		
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{RC}	25		35		45		55		ns
Address Access Time	t _{AA}		25		35		45		55	ns
Data Hold from Address Change	t _{OH}	4		4		4		4		ns
Chip Select Access	t _{ACS}		25		35		45		55	ns
Output Enable to Output Valid	t _{OE}		15		20		25		30	ns
Chip Select to Output in Low Z	t _{CLZ} ¹	5		5		5		5		ns
Output Enable to Output in Low Z	t _{OLZ} ¹	0		0		0		0		ns
Chip deselect to Output in High Z	t _{CHZ} ¹		12		15		20		25	ns
Output disable to Output in High Z	t _{OHZ} ¹		12		15		20		25	ns

1. This parameter is guaranteed by design but not tested.

Parameter	Symbol	Limits								Unit
Read Cycle:		- 70		- 85		- 100		- 120		
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{RC}	70		85		100		120		ns
Address Access Time	t _{AA}		70		85		100		120	ns
Data Hold from Address Change	t _{OH}	5		5		5		5		ns
Chip Select Access	t _{ACS}		70		85		100		120	ns
Output Enable to Output Valid	t _{OE}		35		40		45		50	ns
Chip Select to Output in Low Z	t _{CLZ} ¹	5		5		5		5		ns
Output Enable to Output in Low Z	t _{OLZ} ¹	0		0		0		0		ns
Chip deselect to Output in High Z	t _{CHZ} ¹		30		35		40		50	ns
Output disable to Output in High Z	t _{OHZ} ¹		30		35		40		50	ns

1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT



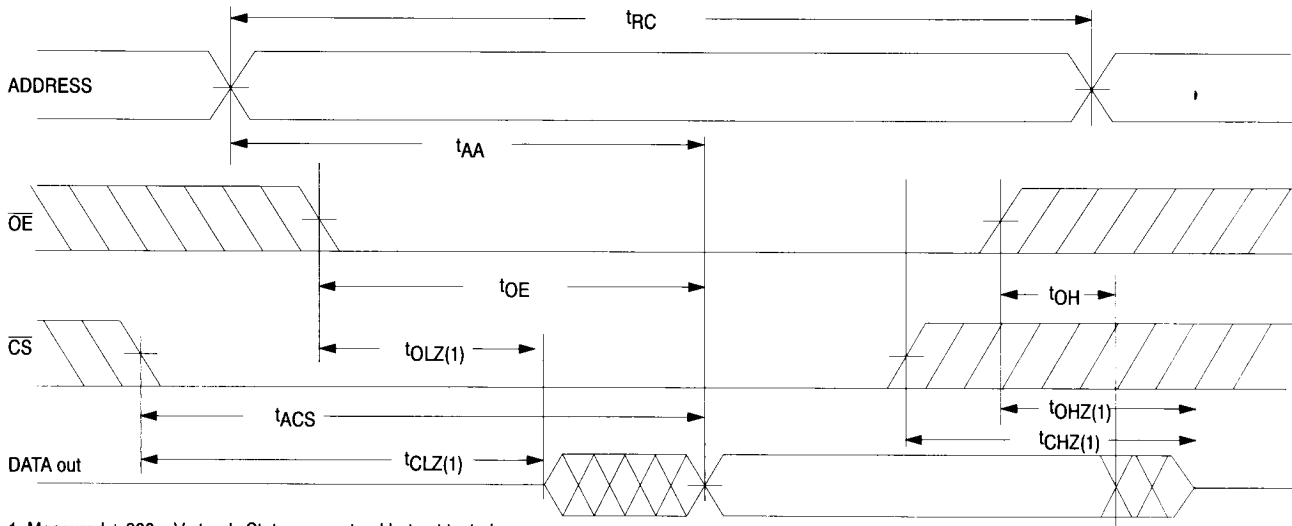
AC TEST CONDITIONS

Parameters	Typ.	Unit
Input Pulse Levels	$V_{IL} = 0$, $V_{IH} = 3.0$	V
Input Rise and Fall Time	5	ns
Input Timing Reference Level	1.5	V
Output Timing Reference Level	1.5	V

Notes:

V_Z is programmable from -2 V to $+7\text{ V}$
 I_{OL} & I_{OH} programmable from 0 to 16 mA
 Tester Impedance $Z_0 = 75\Omega$
 V_Z is typically the midpoint of V_{OH} and V_{OL}
 (i.e. $(2.4 + 0.4)/2 = 1.4\text{ V}$)
 I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit
 D.U.T. Device Under Test
 C_{eff} Effective Capacitance
 ATE Tester Includes Jig Capacitance

READ CYCLE TIMING DIAGRAM



1. Measured ± 200 mV steady State; guaranteed but not tested.

AC CHARACTERISTICS ($V_{CC} = 5$ V, $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$)

Parameter	Symbol	Limits								Unit
Write Cycle:		- 25		- 35		- 45		- 55		
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	t_{WC}	25		35		45		55		ns
Chp Select to End of Write	t_{CW}	20		30		40		45		ns
Address Valid to End of Write	t_{AW}	20		30		40		45		ns
Data to Write-Time Overlap	t_{DW}	15		18		20		25		ns
Data Hold from Write Time	t_{DH}	3		3		3		5		ns
Write Pulse Width	t_{WP}	20		25		35		40		ns
Address Setup Time	t_{AS}	0		0		0		0		ns
Write Recovery Time	t_{WR}	0		0		0		0		ns
Output Active from End of Write	t_{OW}^1	5		5		5		5		ns
Write to Output in High Z	t_{WHZ}^1		10		15		15		20	ns

Parameter	Symbol	Limits								Unit
Write Cycle:		- 70		- 85		- 100		- 120		
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	t_{WC}	70		85		100		120		ns
Chp Select to End of Write	t_{CW}	65		80		90		110		ns
Address Valid to End of Write	t_{AW}	65		80		90		110		ns
Data to Write-Time Overlap	t_{DW}	30		35		40		55		ns
Data Hold from Write Time	t_{DH}	5		5		5		5		ns
Write Pulse Width	t_{WP}	45		50		55		65		ns
Address Setup Time	t_{AS}	5		5		5		5		ns
Write Recovery Time	t_{WR}	0		0		0		0		ns
Output Active from End of Write	t_{OW}^1	5		5		5		5		ns
Write to Output in High Z	t_{WHZ}^1		30		35		40		50	ns

1. This parameter is guaranteed by design but not tested.

The diagram illustrates the timing relationships for a memory device. The signals and their timing parameters are as follows:

- ADDRESS:** The duration of a valid address is t_{WC} .
- $\overline{OE}$ (Output Enable):** The output data is valid while $\overline{OE}$ is active low. The time from the last address change to the output becoming high-impedance is $t_{OHZ(2)}$.
- $\overline{CS}$ (Chip Select):** The duration of a valid chip select is t_{AW} .
- $\overline{WE}$ (Write Enable):**
 - t_{AS} : Address setup time before $\overline{WE}$ goes active.
 - $t_{WP(3)}$: Write pulse width.
 - t_{WR} : Write recovery time after $\overline{WE}$ goes inactive.
- DATA out:**
 - (1) Data is valid during the first access.
 - (1) Data is valid during the second access.
 - $t_{OW(2)}$: Output hold time after the last data change.
- DATA in:**
 - t_{DW} : Data setup time before the write enable pulse.
 - t_{DH} : Data hold time after the write enable pulse.
 - DATA VALID:** The period during which data is valid for writing.

1. I/O pins are in their output state, input signals must not be applied.
2. This parameter is guaranteed by design but not tested.
3. A write occurs during the overlap (t_{WP}) of a low $\overline{CS}$ and a low $\overline{WE}$.

The drawing shows the mechanical specifications for the 10-pin connector. The top view shows a square footprint with overall dimensions of $1.185 (30.1 \text{ mm}) \pm 0.015 (.38 \text{ mm})$ SQ. and a central square area of $1.085 (27.6 \text{ mm}) \pm 0.005 (.127 \text{ mm})$ SQ. (SR). The side view shows a height of $1.0" (25.4 \text{ mm})$. The bottom view shows the pin layout with dimensions: $0.240 (6.1 \text{ mm})$ Max. for the pin pitch, $0.030 (0.76 \text{ mm})$ REF. (SR) for the pin width, $0.135 (3.43 \text{ mm}) \pm 0.005 (.127 \text{ mm})$ SQ. (SR) for the pin spacing, $0.050 (0.9 \text{ mm}) \pm 0.005 (.127 \text{ mm})$ for the pin width, $0.035 (0.9 \text{ mm}) \pm 0.005 (.127 \text{ mm})$ for the pin spacing, $0.040 (1.0 \text{ mm})$ TYP. for the pin width, $0.018 (0.46 \text{ mm})$ TYP. for the pin spacing, $0.600 (15.24 \text{ mm})$ for the pin pitch, $1.0" (25.4 \text{ mm})$ for the pin pitch, $0.100 (2.54 \text{ mm})$ TYP. for the pin pitch, and $0.150" (3.81 \text{ mm})$ Max. for the pin pitch.